



## Final Product Change Notification

201601001F01

**Issue Date:** 13-May-2016  
**Effective Date:** 25-Aug-2016

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# QUALITY

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

**Change of bond wire from Au to Cu and release of 2nd source mold compounds in SOT223**

### Details of this Change

Scheduled changes affect product types in SOT223 package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
- (2) Second source mold compound suppliers will be introduced for copper wire products.
- (3) Some product types will be changed to a new leadframe design. Please see the Self Qualification Report for details.

Old product: wire material is Au (with currently used mold compound suppliers and leadframe design)  
Changed product: wire material is Cu (with currently used and new second source mold compound suppliers, partly changed leadframe design) or Au (with currently used and new second source mold compound suppliers, partly changed leadframe design)

The design and materials of all other components remain unchanged, i.e. no change of die and die attach. Reliability qualification and full electrical characterization over temperature has been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

### Why do we Implement this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy and second source material availability, new second source mold

compounds will be added to the BOM. The second sources are already well-established mold compound suppliers for NXP GA discrete semiconductor products.

(3) Standardisation of leadframe design with similar package SOT89. Leadframes with grooves are in production for SOT89 types since 2006.

#### **Identification of Affected Products**

Top side marking

Products can be identified by different date code formats on package surface:

Products with gold (Au) wire have a 2-digit date code.

Products with copper (Cu) wire will have a 3-digit date code.

### **Product Availability**

#### **Sample Information**

Samples are available upon request

Latest sample request date for PCN samples is 13-June-2016.

#### **Production**

Planned first shipment 25-Aug-2016

#### **Impact**

No impact to the products' functionality anticipated.

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Jun-2016.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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